| ABSOCIATION CONNECTING<br>LECTRONICS INDUSTRIES® INCLUSTRIES | PC. Bannock   | burn, Illinois, A           | ll rights reserved nations. | under both              | This docum<br>level parts, | ent is a declarati<br>the declaration e | on of the su                        | ibstances v<br>s all lower | within the manufactule level materials for v | urer listed which the    | item. Note<br>nanufactu         | e: if the item is an as<br>arer has engineering | sembly with lower responsibility. |  |
|--|---------------|-----------------------------|-----------------------------|-------------------------|----------------------------|---|-------------------------------------|----------------------------|--|--------------------------|---------------------------------|---|-----------------------------------|--|
| IPC Web Site for Information on IPC-1752 Standard Fo         |               |                             |                             | Form Type<br>Distribute |                            |   |                                     |                            | rials and N                                  | ials and Mfg Information |                                 |   |                                   |  |
| Supplier Information   |               |                             |                             |                         |                            |   |                                     |                            |  |                          |                                 |   |                                   |  |
| Company name*  | Company uni   | Company unique ID           |                             |                         | Unique ID Authority        |   |                                     |                            |  | Response Date*           |                                 |   |                                   |  |
| onsemi   |               |                             |                             |                         |                            |   |                                     |                            |  | 2024-05                  | 2024-05-23                      |   |                                   |  |
| Contact Name Title - Contact                                 |               |                             | et                          |                         |                            |   | Phone - Contact*                    |                            |  |                          | Email - Contact*                |   |                                   |  |
| Product-Env-Stewards Product E                               |               |                             | t Enviro Compliance         |                         |                            | NA                                      |                                     |                            |  | Produ                    | Product-Env-Stewards@onsemi.com |   |                                   |  |
| Authorized Representative* Title - Representativ             |               |                             | sentative                   | atative                 |                            | Phone - Representative*                 |                                     |                            | Email -                                      | Email - Representative*  |                                 |   |                                   |  |
| Product-Env-Stewards Prod                                    |               |                             | Product Enviro Compliance   |                         |                            | NA                                      |                                     |                            |  | Produ                    | Product-Env-Stewards@onsemi.com |   |                                   |  |
| Requester Item Number  | Mfr Iter      | n Number                    | Mfr Item Name               |                         |                            | Effective Date                          | ate Version Manufacturing Site      |                            |  | Weight*                  | UOM                             | Unit Type                                       |                                   |  |
|  | NCV78<br>G    | CV78703MW0AR2 3PH BOOST CON |                             | ONTROLLER SP            | PI                         | 2024-05-23                              |                                     | P                          | PHG  |                          | 74.7                            | mg  | Each                              |  |
| Manufacturing Proccess Informa                               | tion          |                             |                             |                         |                            |   |                                     |                            |  |                          |                                 |   |                                   |  |
| Terminal Plating / Grid Array M                              | aterial       | rial Terminal Base Alloy    |                             | J-STD-020 MSI           | TD-020 MSL Rating          |   | Peak Process Body Temperature Max T |                            | e Max Time at Peal                           | k Tempera                | ture Nui                        | mber of Reflow Cy                               | cles                              |  |
| Matte Tin (Sn) - annealed CU All                             |               | CU Alloy                    | 1                           |                         |                            | <b>260</b> C                            |                                     | С                          | <b>30</b> seco                               |                          | seconds 3                       |   |                                   |  |
| Comments   |               |                             |                             |                         |                            |   |                                     |                            |  |                          |                                 |   |                                   |  |
| level 1 - maximum time at peak temperatu                     | are during so | oldering is 10-3            | 0 seconds                   |                         |                            |   |                                     |                            |  |                          |                                 |   |                                   |  |
| For more information regarding material                      | composition   | please refer to             | page 3                      |                         |                            |   |                                     |                            |  |                          |                                 |   |                                   |  |

| RoHS Material Composition Declaration  |  |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|--|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>y others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the   | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and cc<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa  | ances per the definitio  | on above  | Supplier Acceptance                             | * Accepted  |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per   | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |  |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester  | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska  | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance                    | CAS              | Exempt | Weight  | Unit of Measure |
|----------------------|--------|-----------------|----------|------------------------------|------------------|--------|---------|-----------------|
| Die                  | 6.32   | mg              | Supplier | Silicon (Si)                 | 7440-21-3        |        | 6.32    | mg              |
| Die Attach           | 2.6    | mg              | Supplier | Silver (Ag)                  | 7440-22-4        |        | 2.21    | mg              |
|                      |        |                 | Supplier | Acrylic resins               | Proprietary Data |        | 0.39    | mg              |
| Lead Frame           | 35.95  | mg              | Supplier | Silver (Ag)                  | 7440-22-4        |        | 0.719   | mg              |
|                      |        |                 | Supplier | Tin (Sn)                     | 7440-31-5        |        | 0.0899  | mg              |
|                      |        |                 | Supplier | Zinc (Zn)                    | 7440-66-6        |        | 0.0791  | mg              |
|                      |        |                 | Supplier | Chromium (Cr)                | 7440-47-3        |        | 0.0899  | mg              |
|                      |        |                 | Supplier | Copper (Cu)                  | 7440-50-8        |        | 34.9722 | mg              |
| Mold Compound-Black  | 28.97  | mg              | Supplier | Silica Amorphous (SiO2)      | 7631-86-9        |        | 2.3176  | mg              |
|                      |        |                 | Supplier | Carbon Black (C)             | 1333-86-4        |        | 0.1449  | mg              |
|                      |        |                 | Supplier | Aluminum Hydroxide (Al(OH)3) | 21645-51-2       |        | 0.5794  | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)          | 60676-86-0       |        | 22.7414 | mg              |
|                      |        |                 | Supplier | Ortho-Cresol Novolac Resin   | 29690-82-2       |        | 2.3176  | mg              |
|                      |        |                 | Supplier | Phenolic Resin (Novolac)     | 9003-35-4        |        | 0.8691  | mg              |
| Plating              | 0.29   | mg              | Supplier | Tin (Sn)                     | 7440-31-5        |        | 0.29    | mg              |
| Wire Bond - Au       | 0.57   | mg              | Supplier | Gold (Au)                    | 7440-57-5        |        | 0.57    | mg              |